



NXT-DSA

High environmental resistance for dual interface solutions

Linxens NXT-DSA is the industry reference for dual solutions. The versatility of NXT-DSA enables convenience for various applications that require environmental exposures or long life-span need.

Key Features

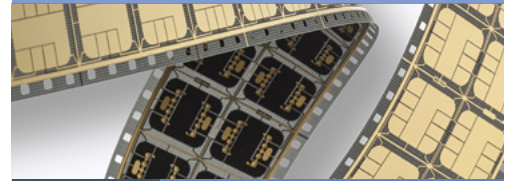
- Worldwide reference plating family
- High corrosion resistance
- Dual interface solution

Typical Product Designs

Part Number	Modules	Cavity	Chip Dimension
9X36008	8	No	4.1 x 3.9 mm
9X33217	8	No	4.1 x 6.4 mm
9X23207	8	No	5.6 x ≤ 8 mm
9X12106	8	✓	2.44 x 2.44 mm
9X12107	8	✓	2.44 x 2.44 mm
9X12110	8	No	3.6 x 3.6 mm



MICROCONNECTORS



Overview

Material

- Film base: Copper-clad Epoxy glass
- Adhesive: High temperature modified Epoxy MCHT
- Copper: ED29µ

Thickness

- Total: 159 ± 20 µm / 165 ± 20 µm
- Plating Thickness
 - Contact side:
 - Ni: 2.0 (-0.6 +1.0) µm
 - Au: 0.07 ± 0.04 µm
 - Back side:
 - Ni: 5.0 (-2.0 +5.0) µm
 - Au: 0.3 (-0.1 +0.6) µm

Temperature Resistance

- 3 minutes at 260°C
- 21 hours at 160°C

Plating Performance

Corrosion resistance: High
Chemical resistance: High

Compliance Labels

- ISO 10373
- ISO 7810

Application Area

- Financial services
- eGovernment
- Healthcare
- IoT
- Leisure and entertainment
- Transportation

Options

- Gold / Palladium
- Micro-etched / Fully-etched
- Colored tape: Red, blue, orange